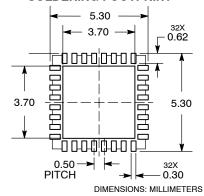


## **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering

## QFN32 5x5, 0.5P

**DATE 07 FEB 2012** 

## NOTES:

- AND ES.

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1		0.05	
А3	0.20 REF		
b	0.20	0.30	
D	5.00 BSC		
D2	3.40	3.60	
E	5.00 BSC		
E2	3.40	3.60	
е	0.50 BSC		
K	0.20		
L	0.30	0.50	
L1		0.15	

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location Α

WL = Wafer Lot ΥY = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.			
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**DESCRIPTION:** TDFN8, 2X3, 0.5P **PAGE 1 OF 1**